

June 15, 2026

TO: Channel

Notice: Change of Polyimide Material used in Wafer Process

We would like to express our sincere appreciation for your continued business and support.

We would like to inform you that we are planning to change the polyimide material used in our wafer process. This change is based on a notification from our supplier, Asahi Kasei, regarding the discontinuation (End-of-Life) of the current polyimide material. While we have held discussions to explore continued supply, we have determined that ensuring a stable long-term supply requires us to transition to an alternative material.

We are currently conducting a thorough evaluation of the replacement polyimide and are working to ensure equivalent quality and reliability.

We sincerely apologize for this sudden notice and any inconvenience it may cause. We appreciate your understanding and cooperation.

- ◆ Applicable products: see Appendix
- ◆ Details of the change: Polyimide Material Supplier
- ◆ Schedule: Mass Production (MP) delivery: April 2027 onward
 - The shipping schedule may vary depending on order quantities and inventory conditions. During the transition period, both existing and new products may be shipped concurrently. Further details will be provided separately by our sales representatives.

If you have any inquiries, please contact our sales representatives by July 31st, 2026.

Sincerely yours,
SEIKO EPSON CORPORATION

Product list:

Product Number	Technical Document
S1C63709D02S000	SP_01-29_Die_AL_ga_e.pdf
S1C63709D03N000	SP_01-29_Die_AL_ga_e.pdf
S1D13506F00A200	SP_01-2_QFP_g_e.pdf
S1D13715B00B200	SP_01-20_BGA_g_e.pdf
S1D13715F01A200	SP_01-02_QFP_g_e.pdf
S1D13719B00B100	SP_01-20_BGA_g_e.pdf
S1D13781F00A100	SP_01-2_QFP_g_e.pdf
S1D13L01F00A100	SP_01-2_QFP_g_e.pdf
S2R72A54F12E300	SP_01-04_QFP_a_e.pdf